

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	4774	MEMS or microelectromechanical or micromechanical or (micro adj (mechanical or electromechanical or (electro adj mechanical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 10:35
2	L8	242	1 and ((resin resist photoresist epoxy polymer organic) near15 (sacrificial spacer removable disposable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:47
3	L15	641	1 and sealed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 10:38
4	L22	62	8 and sealed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:27
5	L29	2991	microfabricat\$3 or (micro adj fabricat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:28
6	L36	7288	1 29	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:28
7	L43	52	29 and 8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:46
8	L50	7285	micromachin\$3 or (micro adj machin\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:47
9	L57	1077	50 and sealed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:48
10	L64	249	50 and ((resin resist photoresist epoxy polymer organic) near15 (sacrificial spacer removable disposable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:48
11	L71	78	64 and sealed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 11:52
12	L78	12846	36 50	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 12:22
13	L85	118	78 and (vapor near3 etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 12:23
14	L92	19	85 and (vapor near3 etch\$3 near20 (HF or hydrofluoric))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 14:02
15	L99	9	("5083857" "5099353" "5018256" "5142405").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/05/31 14:03